



## 74LVC273A

### OCTAL D-TYPE FLIP-FLOP WITH CLEAR

## Description

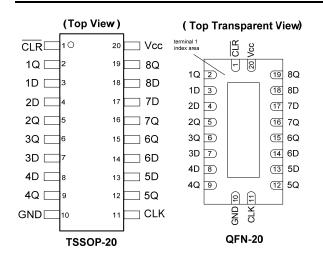
The 74LVC273A provides eight positive-edge-triggered D-type flipflops with a direct clear (CLR) input.

The device is designed for operation with a power supply range of 1.65V to 3.6V. The device is fully specified for partial power down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output preventing damaging current backflow when the device is powered down.

### **Features**

- Supply Voltage Range from 1.65V to 3.6V
- Sinks or Sources 24mA at V<sub>CC</sub> = 3V
- CMOS Low Power Consumption
- IOFF Supports Partial Power Down Operation
- Inputs or Outputs accept up to 5.5V
- Inputs Can Be Driven by 3.3V or 5V Allowing for Mixed Voltage Applications
- Schmitt Trigger Action at All Inputs
- Typical V<sub>OLP</sub> (Quiet Output Ground Bounce) less than 0.8V with  $V_{CC}$  = 3.3V and  $T_A$  = +25°C
- Typical V<sub>OHV</sub> (Quiet Output dynamic VOH) greater than 2.0V with  $V_{CC}$  = 3.3V and T<sub>A</sub> = +25°C
- ESD Protection Tested per JESD 22
  - Exceeds 200-V Machine Model (A115-A)
  - Exceeds 2000-V Human Body Model (A114-A)
  - Exceeds 1000-V Charged Device Model (C101C)
  - Latch-Up Exceeds 250mA per JESD 78, Class II
- All devices are:
  - Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
  - Halogen and Antimony Free. "Green" Device (Note 3)

## Pin Assignments



### Applications

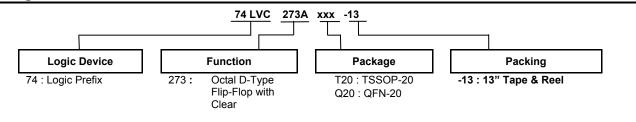
- General Purpose Logic
- Bus Driving
- Power Down Signal Isolation
- Wide array of products such as:
  - PCs, Notebooks, Netbooks, Ultrabooks
  - Networking Computer Peripherals, Hard Drives, CD/DVD ROM
  - TV, DVD, DVR, Set Top Box

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
  - 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



## **Ordering Information**



Device	Package	Package	Package	13" Tape a	nd Reel
Device	Code	(Note 4 & 5)	Size	Quantity	Part Number Suffix
74LVC273AT20-13	T20	TSSOP-20	6.4mm X 6.5mm X 1.2mm 0.65 mm lead pitch	2500/Tape & Reel	-13
74LVC273AQ20-13	Q20	V-QFN4525-20	2.5mm X 4.5mm X 0.95mm 0.50 mm lead pitch	2500/Tape & Reel	-13

4. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf. Notes:

Logic Diagram

5. V-QFN4525-20 is a JEDEC recognized naming convention that specifies the package thickness category as V and the number 4525 describes the package as 4.5mm X 2.5mm.

# **Pin Descriptions**

Pin Number	Pin Name	Description
1	CLR	Clear
2	Q1	Latch Output
3	D1	Data Input
4	D2	Data Input
5	Q2	Latch Output
6	Q3	Latch Output
7	D3	Data Input
8	D4	Data Input
9	Q4	Latch Output
10	GND	Ground
11	CLK	Clock
12	Q5	Latch Output
13	D5	Data Input
14	D6	Data Input
15	Q6	Latch Output
16	Q7	Latch Output
17	D7	Data Input
18	D8	Data Input
19	Q8	Latch Output
20	Vcc	Supply Voltage

#### сік CLR<sup>1</sup> D1\_\_\_\_ 2\_Q1 D >C <u>5</u> Q2 D2-4 D ⊳c D3-7 <u>6</u>Q3 Q D >C D4— 9 Q4 D ⊳C R D5<u>13</u> 12 Q5 0 D ⊳c R D6<u>14</u> 15 Q6 ⊳c D7 17 <u>16</u> Q7 -D Q ->C -R D8<u>18</u> <u>19</u> Q8

# (Each Flip-Flop) INPUTS OUTPUT

**Function Table** 

CLR	CLK	D	Q
L	Х	Х	L
Н	$\uparrow$	Н	Н
Н	$\uparrow$	L	L
Н	L	Х	Q <sub>0</sub>



## Absolute Maximum Ratings (Notes 6 & 7)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V <sub>cc</sub>	Supply Voltage Range	-0.5 to +7.0	V
VI	Input Voltage Range	-0.5 to +7.0	V
I <sub>IK</sub>	Input Clamp Current VI< 0V	-20	mA
Ι <sub>οκ</sub>	Output Clamp Current Vo< 0V	-50	mA
lo	Continuous output current $-0.5V < V_{\odot} V_{cc} + 0.5V$	±50	mA
I <sub>cc</sub>	Continuous Current Through V <sub>cc</sub>	100	mA
	Continuous Current Through GND	-100	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
P <sub>TOT</sub>	Total Power Dissipation	500	mW

Notes: 6. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

7. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

# Recommended Operating Conditions (Note 8)

Symbol	Parameter	Conditions	Min	Max	Unit
V	Supply Voltage	Operating	1.65	3.6	V
V <sub>cc</sub>	Supply Voltage	Data Retention Only	1.5	—	V
VI	Input Voltage	—	0	5.5	V
Vo	Output Voltage	—	0	V <sub>cc</sub>	V
		$V_{CC} = 1.65V$	—	-4	
	Lligh Lovel Output Current	$V_{CC} = 2.3V$	—	-8	mA
I <sub>OH</sub>	High-Level Output Current	V <sub>CC</sub> = 2.7V	—	-12	mA
		V <sub>CC</sub> = 3.0V	—	-24	
		V <sub>CC</sub> = 1.65V	—	4	
	Low Lovel Output Current	$V_{CC} = 2.3V$	—	8	mA
I <sub>OL</sub>	Low-Level Output Current	V <sub>CC</sub> = 2.7V	—	12	mA
		V <sub>CC</sub> = 3.0V	—	24	
Δt/ΔV	Input Transition Rise or Fall Rate		_	10	ns/V
T <sub>A</sub>	Operating Free-Air Temperature		-40	+125	°C

Note: 8. Unused inputs should be held at  $V_{CC}$  or ground.



# **Electrical Characteristics**

Oursela al	Devenuetev	r Test Conditions		N/	T <sub>A</sub> = -40°0	C to +85°C	T <sub>A</sub> = +85°C	to +125°C	Unit
Symbol	Parameter	Farameter Test Conditions	attons	is V <sub>cc</sub>	Min	Max	Min	Max	Unit
				1.65V to 1.95V	V <sub>CC</sub> X 0.65		V <sub>CC</sub> X 0.65		
VIH	High-Level Input Voltage			2.3V to 2.7V	1.7		1.7		V
	vollage			3.0V to 3.6V	2		2		
				1.65V to 1.95V		V <sub>CC</sub> X 0.35		V <sub>cc</sub> X 0.35	
VIL	Low-Level Input voltage			2.3V to 2.7V		0.7		0.7	V
	voltage			3.0V to 3.6V		0.8		0.8	
		I <sub>он</sub> = -50µА		1.65V to 3.6V	V <sub>CC</sub> -0.2		V <sub>cc</sub> -0.3		
		I <sub>он</sub> = -4mA		1.65V	1.2		1.05		
V	High-Level Output Voltage	I <sub>он</sub> = -8mA		2.3V	1.7		1.65		
V <sub>OH</sub>		I <sub>он</sub> = -12mA		2.7V	2.2		2.05		V
			3.0V	2.4		2.48		v	
		I <sub>он</sub> = -24mA		3.0V	2.3		2.0		
		I <sub>OL</sub> = 100μA		1.65V to 3.6V		0.2		0.3	
		I <sub>OL</sub> = 4mA		1.65V		0.45		0.65	
Vol	Low-Level Output Voltage	I <sub>OL</sub> = 8mA		2.3V		0.60		0.80	V
	Voltage	I <sub>OL</sub> = 12mA		2.7V		0.40		0.60	
		I <sub>OL</sub> = 24mA		3.0V		0.55		0.80	
I <sub>OFF</sub>	Power Down Leakage Current	$V_1$ or $V_0 = 0$ or	5.5V	0V		±10		20	μA
I,	Input Current Control Pins	V <sub>I</sub> = GND or 5	.5V	0 to 3.6V		±5		± 20	μA
Icc	Supply Current	$V_1 = GND \text{ or } V_{CC_1} I_0 = 0$		6.0V		10		40	μA
$\Delta I_{CC}$	Additional Supply Current	One input at Vcc-0.6V lo = 0A		2.7V to 3.6V		500		5000	μA
0	Input	Control Pins	$V_I = GND$	0)(4= 2.0)(	4.0 t	ypical	4.0 t	/pical	
Ci	Capacitance	I/O Pins	or V <sub>cc</sub>	0V to 3.6V	5.5 typical		5.5 typical		pF



## **Switching Characteristics**

0 milest	Demonstern	To at O an difficure		1	Γ <sub>A</sub> = +25°	с	-40°C t	o +85°C	+85°C to	o +125°C	Unit
Symbol	Parameter	Test Conditions	V <sub>cc</sub>	Min	Тур	Max	Min	Max	Min	Max	Unit
			1.8V ± 0.15V	35	40		35		30		
£	Maximum	Figure 1	2.5V ± 0.3V	75	60		50		45		N 4 la
f <sub>MAX</sub>	Frequency		2.7V	150	175		150		100		Mhz
		Ī	3.3V ± 0.3	150	230		150		125		
			1.8V ± 0.15V	5.0	2.5		5.0		5.5		
	Pulse Width CLK	Figure 1	2.5V ± 0.3V	4.0	2.0		4.0		4.5		
tw	-		2.7V	3.3	1.7		3.3		3.5		ns
	High or Low		3.3V ± 0.3V	3.0	1.5		3.0		3.5		
			1.8V ± 0.15V	5.0	2.5		5.0		5.5		
4	Pulse Width	Figure 1	2.5V ± 0.3V	4.0	2.0		4.0		4.5		
t <sub>w</sub>	CLR Low		2.7V	3.3	1.7		3.3		3.5		ns
			3.3V ± 0.3V	3.0	1.5		3.0		3.5		
	Set-up Time D <sub>N</sub>		1.8V ± 0.15V	4.0	2.0		4.0		4.5	t <sub>s∪</sub>	
		Figure 1	2.5V ± 0.3V	3.0	1.5		3.0		3.5		ns
t <sub>su</sub>	to CLK		2.7V	2.0	1.0		2.0		2.5		
		†	3.3V ± 0.3V	1.5	1.0		1.5		2.0		
		Figure 1	1.8V ± 0.15V	3.0	1.5		3.0		3.5		
	Hold Time		2.5V ± 0.3V	2.0	1.0		2.0		2.5		ns
t <sub>H</sub>	D <sub>N</sub> to CLK		2.7V	1.5	1.0		1.5		2.0		
		t t	3.3V ± 0.3V	1.5	1.0		1.5		2.0		
			1.8V ± 0.15V	1	7.8	16.5	1	17	1	14.2	
	Removal Time	Firmer 4	2.5V ± 0.3V	1	4	9	1	9.5	1	8.2	
t <sub>REM</sub>	CLR to CLK	Figure 1	2.7V	1	4.4	8.3	1	8.5	1	10.0	ns
		t t	3.3V ± 0.3V	1.7	4.1	7.3	1.7	7.5	1.7	9.0	
			1.8V ± 0.15V	1	7.8	16.5	1	17	1	14.2	
	Propagation	Fierung d	2.5V ± 0.3V	1	4	9	1	9.5	1	8.2	
t <sub>PD</sub>	Delay CLK to Q <sub>N</sub>	Figure 1	2.7V	1	4.4	8.3	1	8.5	1	10.0	ns
	CLK IO QN	†	3.3V ± 0.3V	1.7	4.1	7.3	1.7	7.5	1.7	9.0	
	Propagation		1.8V ± 0.15V	1	7.8	16.5	1	17	1	14.2	
	Delay	Figure 4	2.5V ± 0.3V	1	4	9	1	9.5	1	8.2	
t <sub>PD</sub>		Figure 1	2.7V	1	4.4	8.3	1	8.5	1	10.0	ns
	$\overline{CLR}$ to $Q_N$	†	3.3V ± 0.3V	1.7	4.1	7.3	1.7	7.5	1.7	9.0	
tsk(0)	Output Skew Time		3.3V ± 0.3V			1.0				1.5	ns

# **Operating Characteristics**

T <sub>A</sub> = +25°C					
Symbol	Parameter	Test Conditions	Vcc	TYP	Unit
	Power dissipation capacitance per gate	F = 10 MHz	1.8V ± 0.15V	9.9	
C <sub>pd</sub>			2.5V ± 0.3V	10.2	pF
·			3.3V ± 0.3V	10.6	

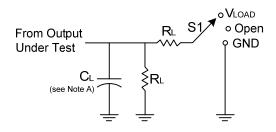
# Package Characteristics

Symbol	Parameter	Package	Test Conditions	Min	Тур	Max	Unit
$\theta_{JA}$	Thermal Resistance Junction-to-Ambient	TSSOP-20	(Note 9)	-	74	—	°C/W
$\theta_{\rm JC}$	Thermal Resistance Junction-to-Case	TSSOP-20	(Note 9)	_	15	_	°C/W
$\theta_{JA}$	Thermal Resistance Junction-to-Ambient	V-QFN4525-20	(Note 9)	_	67	_	°C/W
θ <sub>JC</sub>	Thermal Resistance Junction-to-Case	V-QFN4525-20	(Note 9)	_	20	_	°C/W

Note: 9. Test conditions for TSSOP-20 and V-QFN4525-20: Devices mounted on 4 layer FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout per JESD 51-7.

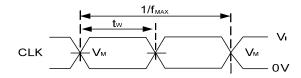


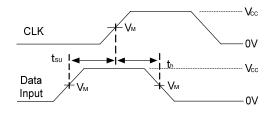
## **Parameter Measurement Information**



TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open

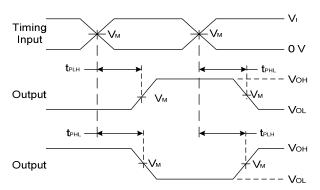
N N	Inp	outs	N	N	•	-	<b>N</b> 4
V <sub>cc</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	RL	VΔ
1.8V ± 0.15V	V <sub>cc</sub>	≤2ns	V <sub>cc</sub> /2	$2 \times V_{CC}$	30pF	1ΚΩ	0.15V
2.5V ± 0.2V	V <sub>cc</sub>	≤2ns	V <sub>cc</sub> /2	$2 \times V_{CC}$	30pF	500Ω	0.15V
2.7V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
3.3V ± 0.3V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V





#### **Voltage Waveform Pulse Duration**

Voltage Waveform Set-up and Hold Times



#### Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

Notes:

A. Includes test lead and test apparatus capacitance. B. All pulses are supplied at pulse repetition rate  $\leq$  10 MHz.

C. Inputs are measured separately one transition per measurement.

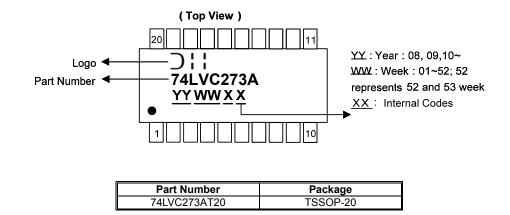
D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{PD.}$ 

Figure 1 Load Circuit and Voltage Waveforms

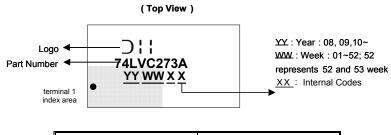


### **Marking Information**

### (1) TSSOP20



### (2) QFN-20 (V-QFN4525-20)



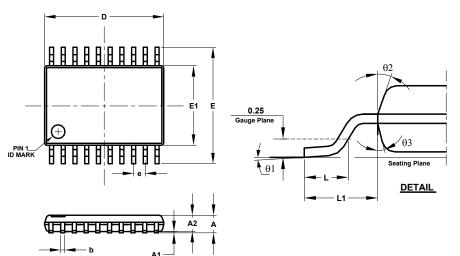
Part Number	Package
74LVC273AQ20	V-QFN4525-20



## Package Outline Dimensions (All Dimensions in mm)

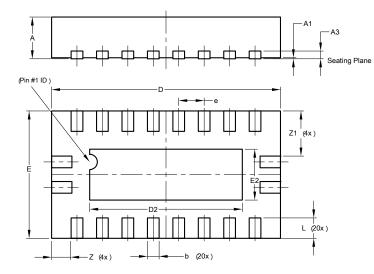
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

(1) TSSOP-20



TSSOP-20				
Dim	Min	Max	Тур	
Α	-	1.20	-	
A1	0.05	0.15	-	
A2	0.80	1.05	-	
b	0.19	0.30	-	
С	0.09	0.20	-	
D	6.40	6.60	6.50	
Е	6.20	6.60	6.40	
E1	4.30	4.50	4.40	
e	0.65 BSC			
L	0.45	0.75	0.60	
L1	1.0 REF			
θ1	0°	8°	-	
θ2	10°	14°	12°	
θ3	10°	14°	12°	
All Dimensions in mm				

### (2) QFN-20 (V-QFN4525-20)



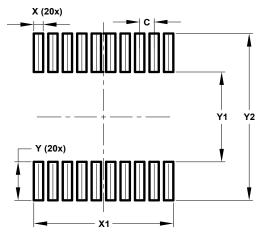
V-QFN4525-20				
Dim	Min	Max	Тур	
Α	0.75	0.85	0.80	
A1	0.00	0.05	0.02	
A3	-	-	0.15	
b	0.18	0.30	0.23	
D	4.45	4.55	4.50	
D2	2.85	3.15	3.00	
E	2.45	2.55	2.50	
E2	0.85	1.15	1.00	
е	0.50BSC			
L	0.30	0.50	0.40	
Z	-	-	0.385	
Z1	-	-	0.885	
All Dimensions in mm				



## Suggested Pad Layout

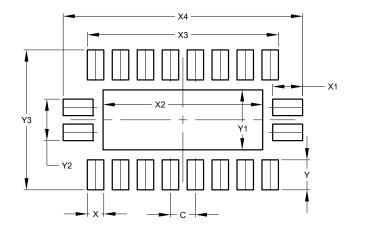
Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

### (1) TSSOP-20



Dimensions	Value (in mm)	
С	0.650	
Х	0.420	
X1	6.270	
Y	1.789	
Y1	4.160	
Y2	7.720	

### (2) QFN-20 (V-QFN4525-20)



Dimensions	Value (in mm)
С	0.500
Х	0.330
X1	0.600
X2	3.200
X3	3.830
X4	4.800
Y	0.600
Y1	1.200
Y2	0.830
Y3	2.800



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